Annotations of Doctoral Thesis Topics for Degree Course "Nanotechnology and Advanced Materials"

Торіс:	Polymers containing highly dispersed phase
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Annotation:

The work will address polymers containing a dispersed phase with dimensions on the micrometer scale with focus on the implementation of their interface adhesion on nano-level into the models describing viscoelastic creep and stress strain behavior.

Requirements:

Knowledge of general and macromolecular chemistry and physics at the university level. Good knowledge of the English language. Basic manual and laboratory work skills. Ability to work independently.

Literature:

- 1. HAENEL, Thomas; HAUSNEROVÁ, Berenika; STEINHAUS, Johannes; MOEGINGER, Ing Bernhard. Qualitative Beam Profiling of Light Curing Units for Resin Based Composites. The European Journal of Prosthodontics and Restorative Dentistry. 2016, vol. 24, no. 4 s. 197-202. ISSN:0965-7452.
- STEINHAUS, Johannes|Hausnerova, Berenika|Haenel, Thomas|Selig, Daniela|Duvenbeck, Fabian|Moeginger, Bernhard. Correlation of Shear and Dielectric Ion Viscosity of Dental Resins

 Influence of Composition, Temperature and Filler Content. Dental Materials. 2016, vol. 32, no. 7 s. 899-907. ISSN:0109-5641.
- Böhm H.J. (2004) Modeling the Mechanical Behavior of Short Fiber Reinforced Composites. In: Böhm H.J. (eds) Mechanics of Microstructured Materials. International Centre for Mechanical Sciences (Courses and Lectures), 464. Springer, Vienna.
- Altenbach H. (2005) Modelling of anisotropic behavior in fiber and particle reinforced composites. In: Sadowski T. (eds) Multiscale Modelling of Damage and Fracture Processes in Composite Materials. CISM International Centre for Mechanical Sciences (Courses and Lectures), vol 474. Springer, Vienna.
- 5. Price C.D., Hine P.J., Whiteside B., Cunha A.M., Ward I.M. (2006) Modelling the elastic and thermoelastic properties of short fibre composites with anisotropic phases. Comp Sci & Tech 66, 1, 69-79.